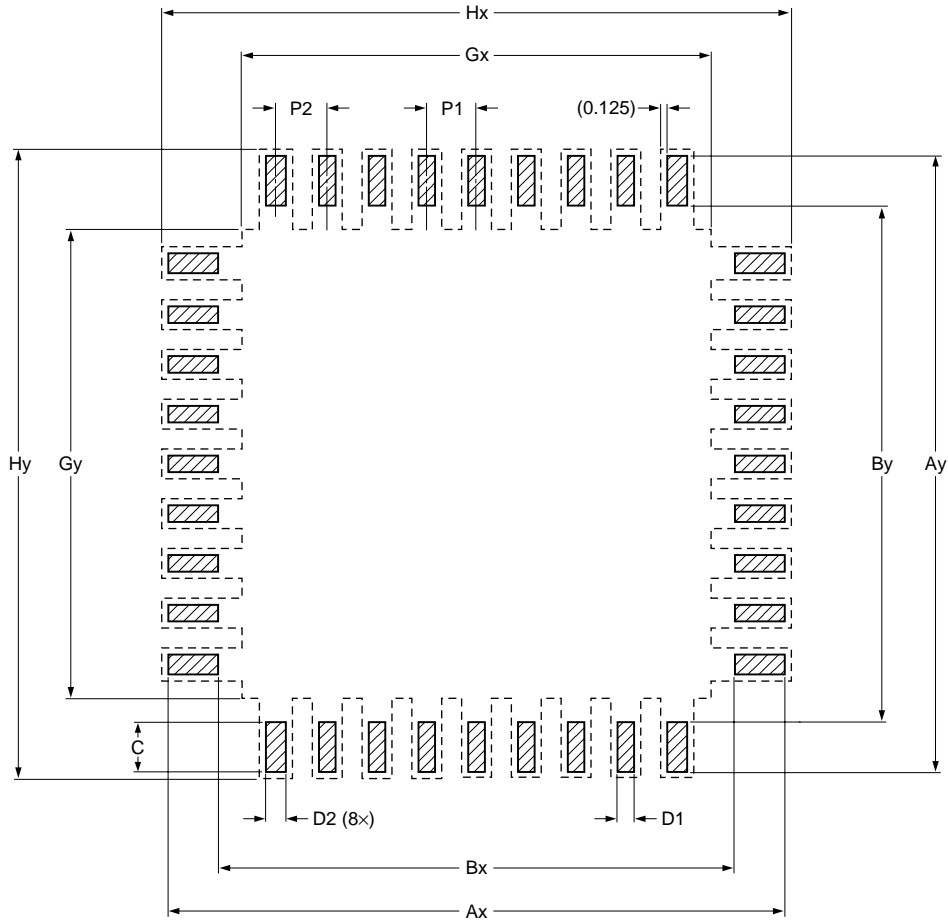



Footprint information for reflow soldering of QFP64 package

SOT393-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	17.900	17.900	14.900	14.900	1.500	0.500	0.600	14.500	14.500	18.150	18.150